捷多邦,专业PCB打样工厂,24小时加急出货

NTR0202PL

Power MOSFET

–20 V, –400 mA, P–Channel SOT–23 Package

Features

- Low $R_{DS(on)}$ Provides Higher Efficiency and Extends Battery Life $R_{DSon} = 0.80 \ \Omega$, $V_{GS} = -10 \ V$
 - $R_{DSon} = 1.10 \Omega, V_{GS} = -4.5 V$
- Miniature SOT-23 Surface Mount Package Saves Board Space
- Pb–Free Package is Available

Applications

- DC–DC Converters
- Computers
- Printers
- PCMCIA Cards
- Cellular and Cordless Telephones

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	V _{DSS}	-20	V
Gate-to-Source Voltage - Continuous	V _{GS}	±20	V
Continuous Drain Current @ T_{A} = 25°C Pulsed Drain Current (t_{p} \leq 10 $\mu s)$	I _D I _{DM}	-0.4 -1.0	A
Total Power Dissipation @ $T_A = 25^{\circ}C$ (Note 1)	PD	225	mW
Operating and Storage Temperature Range	T _J , T _{stg}	– 55 to 150	°C
Thermal Resistance – Junction-to-Ambient	R _{0JA}	556	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 s	ΤL	260	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

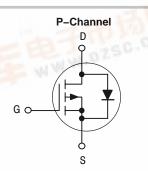
1. Pulse Test: Pulse Width \leq 300 µs, Duty Cycle \leq 2%.

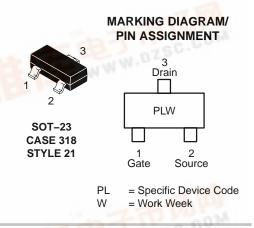


ON Semiconductor®

http://onsemi.com

V _{(BR)DSS}	R _{DS(on)} TYP	I _D MAX
–20 V	550 mΩ @ –10 V	–400 mA





ORDERING INFORMATION

Device	Package	Shipping [†]		
Device	Таскаде	ompping		
NTR0202PLT1	SOT-23	3000 Tape & Reel		
NTR0202PLT1G	SOT-23 (Pb-Free)	3000 Tape & Reel		
NTR0202PLT3	SOT-23	10,000 Tape & Reel		
NTR0202PLT3G	SOT-23 (Pb-Free)	10,000 Tape & Reel		

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.



ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic			Min	Тур	Мах	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage $(V_{GS} = 0 V, I_D = -10 \mu A)$ (Positive Temperature Coefficient)		V _{(BR)DSS}	-20	33		V mV/°C
Zero Gate Voltage Drain Current $(V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 25^{\circ}\text{C})$ $(V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 150^{\circ}\text{C})$		I _{DSS}			-1.0 -10	μΑ
Gate-Body Leakage Current (V _{GS} = :	± 20 V, V _{DS} = 0 V)	I _{GSS}			±100	nA
ON CHARACTERISTICS (Note 2)						
Gate Threshold Voltage $(V_{DS} = V_{GS}, I_D = -250 \mu A)$ (Negative Temperature Coefficient)		V _{GS(th)}	-1.1	-1.9 3.0	-2.3	V mV/°C
Static Drain-to-Source On-Resistant (V_{GS} = -10 V, I_D = -200 m/ (V_{GS} = -4.5 V, I_D = -50 mA)	R _{DS(on)}		0.55 0.80	0.80 1.10	Ω	
Forward Transconductance $(V_{DS} = -10 \text{ V}, \text{ I}_{D} = -200 \text{ m/s})$	9fs		0.5		Mhos	
DYNAMIC CHARACTERISTICS						1
Input Capacitance		C _{iss}		70		pF
Output Capacitance	(V _{DS} = -5.0 V, V _{GS} = 0 V, F = 1.0 MHz)	C _{oss}		74		
Reverse Transfer Capacitance	· · · · · · · · · · · · · · · · · · ·	C _{rss}		26		
	Note 3)					
Turn–On Delay Time		t _{d(on)}		3.0		ns
Rise Time	(V _{DD} = −15 V, I _D = −200 mA,	tr		6.0		
Turn-Off Delay Time	$V_{GS} = -10 \text{ V}, \text{ R}_{G} = 6.0 \Omega$	t _{d(off)}		18		
Fall Time		t _f		4		
Total Gate Charge		Q _{TOT}		2.18		nC
Gate-Source Charge	$(V_{DS} = -15 \text{ V}, I_D = -200 \text{ mA}, V_{GS} = -10 \text{ V})$	Q_{GS}		0.41		
Gate-Drain Charge	,	Q_{GD}		0.40		
BODY-DRAIN DIODE CHARACTER	ISTICS (Note 2)					
Diode Forward Voltage (Note 2) $(I_S = -400 \text{ mA}, V_{GS} = 0 \text{ V})$ $(I_S = -400 \text{ mA}, V_{GS} = 0 \text{ V}, T_J = 150^{\circ}\text{C})$		V _{SD}		-0.8 -0.65	-1.0	V
Reverse Recovery Time		t _{rr}		11.8		ns
	(I _S = −1.0 A, V _{GS} = 0 V, dI _S /dt = 100 A/μs)	t _a		9		1
		t _b		3		1
Reverse Recovery Stored Charge	$(I_{S} = -1.0 \text{ A}, V_{GS} = 0 \text{ V}, \\ dI_{S}/dt = 100 \text{ A}/\mu s)$	Q _{RR}		0.007		μC

Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
Switching characteristics are independent of operating junction temperature.

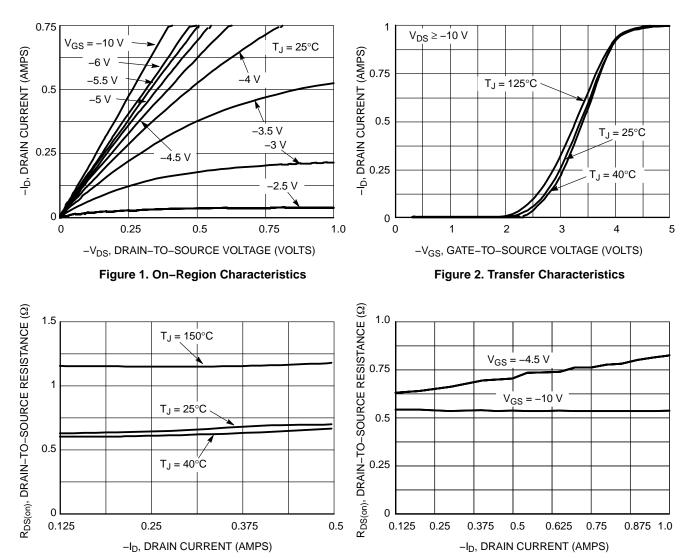
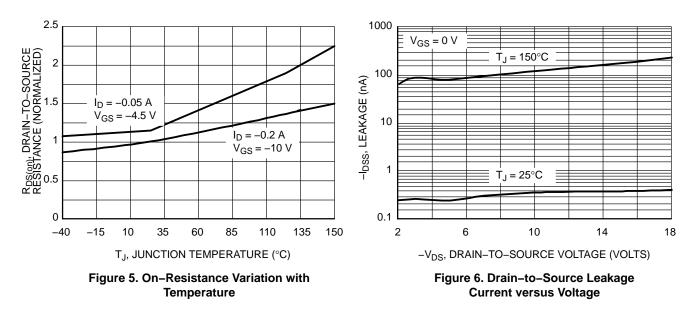
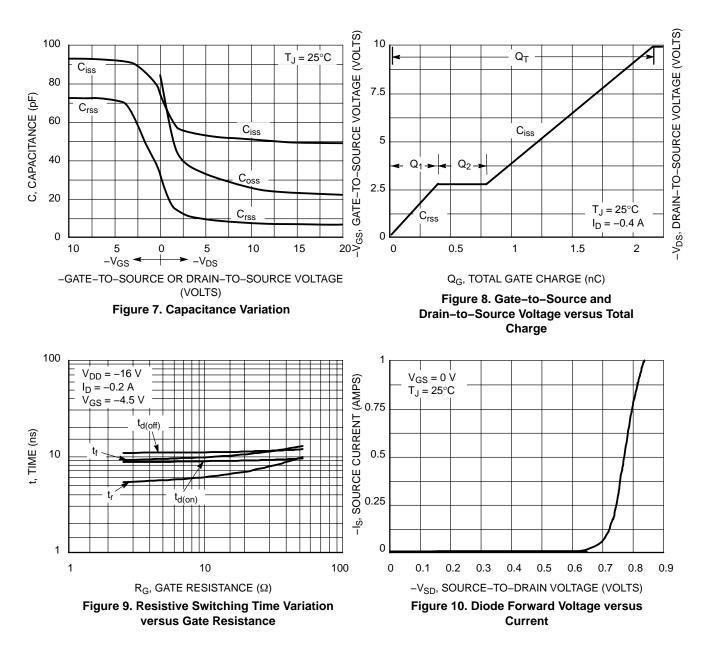


Figure 3. On–Resistance versus Drain Current

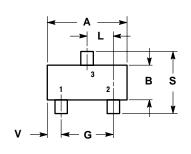


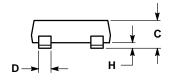


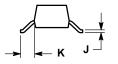


PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-09 ISSUE AJ







- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. MAXIUMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL. 4. 318–01, -02, AND -06 OBSOLETE, NEW STANDARD 318–09.

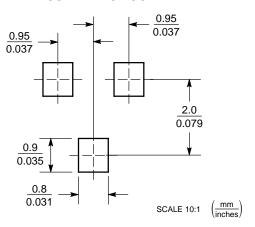
	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.1102	0.1197	2.80	3.04
В	0.0472	0.0551	1.20	1.40
С	0.0385	0.0498	0.99	1.26
D	0.0140	0.0200	0.36	0.50
G	0.0670	0.0826	1.70	2.10
н	0.0040	0.0098	0.10	0.25
J	0.0034	0.0070	0.085	0.177
к	0.0180	0.0236	0.45	0.60
L	0.0350	0.0401	0.89	1.02
S	0.0830	0.0984	2.10	2.50
V	0.0177	0.0236	0.45	0.60

STYLE 21:

PIN 1. GATE 2. SOURCE

3. DRAIN

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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